Hex Buffer

The MC14049B Hex Inverter/Buffer and MC14050B Noninverting Hex Buffer are constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. These complementary MOS devices find primary use where low power dissipation and/or high noise immunity is desired. These devices provide logic level conversion using only one supply voltage, V_{DD}.

The input–signal high level (V_{IH}) can exceed the V_{DD} supply voltage for logic level conversions. Two TTL/DTL loads can be driven when the devices are used as a CMOS–to–TTL/DTL converter ($V_{DD} = 5.0 \text{ V}$, $V_{OL} \le 0.4 \text{ V}$, $I_{OL} \ge 3.2 \text{ mA}$).

Note that pins 13 and 16 are not connected internally on these devices; consequently connections to these terminals will not affect circuit operation.

Features

- High Source and Sink Currents
- High-to-Low Level Converter
- Supply Voltage Range = 3.0 V to 18 V
- V_{IN} can exceed V_{DD}
- Meets JEDEC B Specifications
- Improved ESD Protection On All Inputs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit			
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V			
V _{in}	Input Voltage Range (DC or Transient)	-0.5 to +18.0	V			
V _{out}	Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V			
l _{in}	Input Current (DC or Transient) per Pin	±10	mA			
I _{out}	Output Current (DC or Transient) per Pin	±45	mA			
P _D	Power Dissipation, per Package (Note 1) (Plastic) (SOIC)	825 740	mW			
T _A	Ambient Temperature Range	-55 to +125	°C			
T _{stg}	Storage Temperature Range	-65 to +150	°C			
TL	Lead Temperature (8–Second Soldering)	260	°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: See Figure 3.

This device contains protection circuitry to protect the inputs against damage due to high static voltages or electric fields referenced to the V_{SS} pin only. Extra precautions must be taken to avoid applications of any voltage higher than the maximum rated voltages to this high–impedance circuit. For proper operation, the ranges $V_{SS} \le V_{in} \le 18 \text{ V}$ and $V_{SS} \le V_{OUt} \le V_{DD}$ are recommended.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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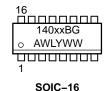


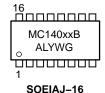
SOIC-16 D SUFFIX CASE 751B SOEIAJ-16 F SUFFIX CASE 966 TSSOP-16 DT SUFFIX CASE 948F

PIN ASSIGNMENT

V _{DD} [1 ●	16	NC
OUT _A [2	15	OUTF
IN _A [3	14] IN _F
OUT _B [4	13	NC
IN _B [5	12	OUT _E
OUT _C [6	11] INE
IN _C [7	10	OUT _D
V _{SS} [8	9	IN _D

MARKING DIAGRAMS







TSSOP-16

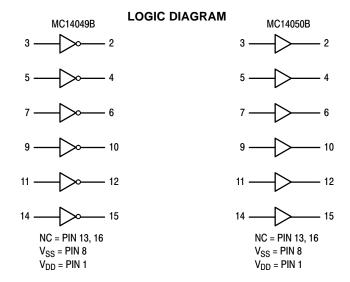
xx = Specific Device Code A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Indicator

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14049BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14049BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14049BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14049BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

MC14050BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14050BDG*	SOIC-16 (Pb-Free)	48 Units / Rail
MC14050BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14050BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14050BDTG	TSSOP-16 (Pb-Free)	96 Units / Rail
NLV14050BDTG*	TSSOP-16 (Pb-Free)	96 Units / Rail
MC14050BDTR2G	TSSOP-16 (Pb-Free)	2500 Units / Tape & Reel
MC14050BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				-55	5°C		+25°C		+12	5°C	
Characterist	ic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD}	"0" Level	V _{OL}	5.0 10 15		0.05 0.05 0.05		0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V _{in} = 0	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage $ (V_O = 4.5 \text{ Vdc}) $ $ (V_O = 9.0 \text{ Vdc}) $ $ (V_O = 13.5 \text{ Vdc}) $	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ Vdc})$ $(V_O = 1.0 \text{ Vdc})$ $(V_O = 1.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	ГОН	5.0 10 15	-1.6 -1.6 -4.7	- - -	-1.25 -1.30 -3.75	-2.5 -2.6 -10	- - -	-1.0 -1.0 -3.0	_ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	3.75 10 30	- - -	3.2 8.0 24	6.0 16 40	- - -	2.6 6.6 19	- - -	mAdc
Input Current		l _{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (Vin =	= 0)	C _{in}	-	-	-	-	10	20	_	-	pF
Quiescent Current (Per	Package)	I _{DD}	5.0 10 15	- - -	1.0 2.0 4.0	- - -	0.002 0.004 0.006	1.0 2.0 4.0	- - -	30 60 120	μAdc
Total Supply Current (No (Dynamic plus Quies per package) (C _L = 50 pF on all ou buffers switching	cent,	Ι _Τ	5.0 10 15			$I_T = (3)$	1.8 μΑ/kHz) f 3.5 μΑ/kHz) f 5.3 μΑ/kHz) f	+ I _{DD}			μAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

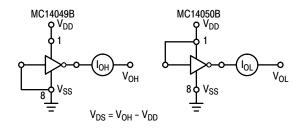
Where: I_T is in μA (per Package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency and k = 0.002.

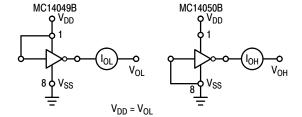
<sup>The formulas given are for the typical characteristics only at +25°C
To calculate total supply current at loads other than 50 pF:</sup>

AC SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}, T_A = +25^{\circ}\text{C}$)

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (0.7 \text{ ns/pF}) C_L + 65 \text{ ns}$ $t_{TLH} = (0.25 \text{ ns/pF}) C_L + 37.5 \text{ ns}$ $t_{TLH} = (0.2 \text{ ns/pF}) C_L + 30 \text{ ns}$	t _{TLH}	5.0 10 15	- - -	100 50 40	160 80 60	ns
Output Fall Time $t_{THL} = (0.2 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{THL} = (0.06 \text{ ns/pF}) C_L + 17 \text{ ns}$ $t_{THL} = (0.04 \text{ ns/pF}) C_L + 13 \text{ ns}$	t _{THL}	5.0 10 15	- - -	40 20 15	60 40 30	ns
Propagation Delay Time $t_{PLH} = (0.33 \text{ ns/pF}) C_L + 63.5 \text{ ns}$ $t_{PLH} = (0.19 \text{ ns/pF}) C_L + 30.5 \text{ ns}$ $t_{PLH} = (0.06 \text{ ns/pF}) C_L + 27 \text{ ns}$	t _{PLH}	5.0 10 15	- - -	80 40 30	140 80 60	ns
Propagation Delay Time $t_{PHL} = (0.2 \text{ ns/pF}) \text{ C}_L + 30 \text{ ns}$ $t_{PHL} = (0.1 \text{ ns/pF}) \text{ C}_L + 15 \text{ ns}$ $t_{PHL} = (0.05 \text{ ns/pF}) \text{ C}_L + 12.5 \text{ ns}$	t _{PHL}	5.0 10 15	- - -	40 20 15	80 40 30	ns

- 5. The formulas given are for the typical characteristics only at 25°C.
 6. Data labeled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.





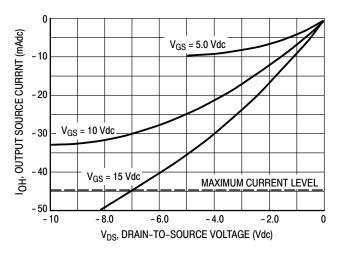


Figure 1. Typical Output Source Characteristics

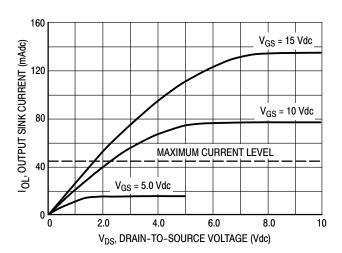


Figure 2. Typical Output Sink Characteristics

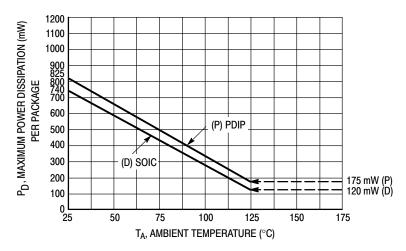


Figure 3. Ambient Temperature Power Derating

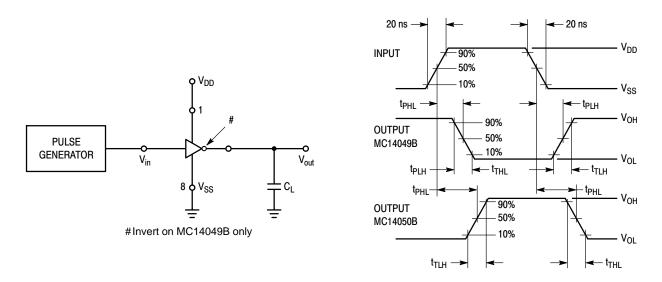
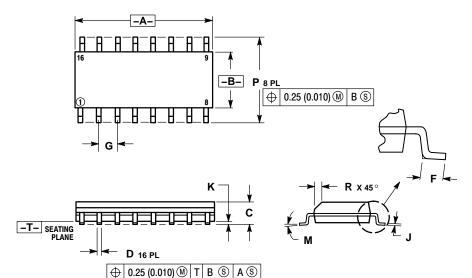


Figure 4. Switching Time Test Circuit and Waveforms

PACKAGE DIMENSIONS

SOIC-16 **D SUFFIX** CASE 751B-05 ISSUE K

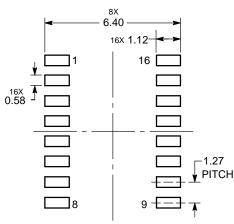


NOTES:

- TES:
 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD
 PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAG
 PROTRUSION. ALLOWABLE DAMBAG PROTRUSION
 SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D
 DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*

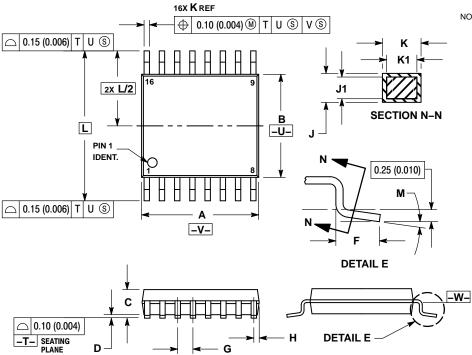


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** CASE 948F ISSUE B



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

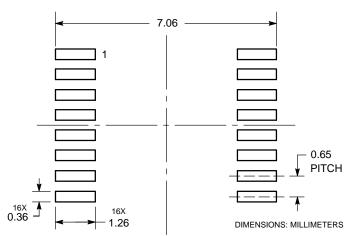
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR

 - 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
M	0°	8°	0°	8 °

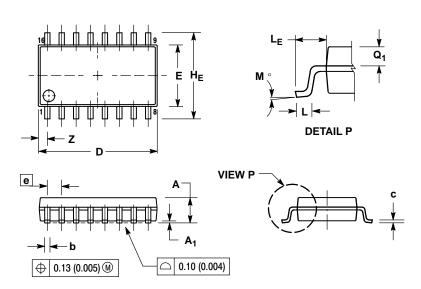
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX CASE 966 ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING DIRECT
 Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE
 TOTAL AND ARE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. I. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 i. THE LEAD WIDTH DIMENSION (b) DOES NOT
- INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
Α ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LΕ	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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 MC14050BDTG
 MC14050BDTR2

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 MC14050BFEL
 MC14050BFELG
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 NLV14050BDG
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